



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

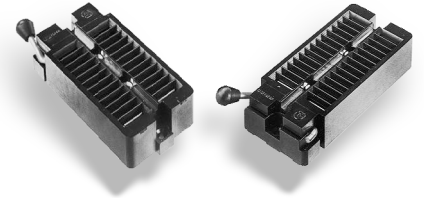




Series 55 Universal Zero-Insertion-Force DIP Test Socket

FEATURES

- Accepts Devices on 0.300 to 0.600 [7.62 to 15.24] Centers
- All Pin Count Sockets go into PCB with either 0.300 or 0.600 [7.62 or 15.24] Centers
- Contacts Normally-closed to Eliminate Dependence on Plastic to Sustain Contact Integrity
- Socket Handle Configured with Closed Contacts (on) when in the Up or Down Position, and Mounted on the Right- or Left-hand Side
- Sockets may be Soldered into PCBs or Plugged into Any Socket or Receptacle



GENERAL SPECIFICATIONS

- **SOCKET BODY:** Black UL 94V-0 glass-filled Polyphenylene Sulfide (PPS)
- **HANDLE:** Stainless Steel
- **HANDLE KNOB:** Brass 360, 1/2-hard
- **CONTACTS:** BeCu 172 per QQ-C-533 **-OR-** Spinodal Alloy
- **ALL BeCu CONTACTS:** 50μ [1.27μ] min. Ni under plate per QQ-N-290, over plated with 200μ [5.08μ] min. matte Sn per ASTM B545-97; **-OR-** 200μ [5.08μ] min. 90/10 Sn/Pb per MIL-T-10727-11 10μ [0.25μ] min. Au per MIL-G-45204
- **SPINODAL CONTACT PLATING:** 50μ [1.27μ] min. NiB
- **HIGH-TEMPERATURE BeNi CONTACT PLATING:** 50μ [1.27μ] NiB
- **CONTACT CURRENT RATING:** 1 amp
- **INSULATION RESISTANCE:** 1000 MΩ min.
- **DIELECTRIC WITHSTANDING VOLTAGE:** 1000 VAC
- **LIFE CYCLE:** 25,000 to 50,000 cycles
- **OPERATING TEMPERATURE:** -85°F to 221°F [-65°C to 105°C] Sn plating; 302°F [150°C] Au plating; 392°F [200°C] NiB plating
- **RETENTION FORCE (closed):** 55g/pin based on a 0.020 [0.51] dia. test lead
- **ACCEPTS LEADS:** 0.015-0.045 [0.38-1.14] wide, 0.110-0.280 [2.79-7.11] long

ORDERING INFORMATION

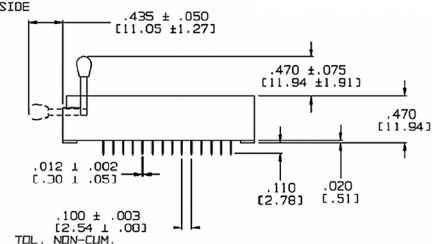
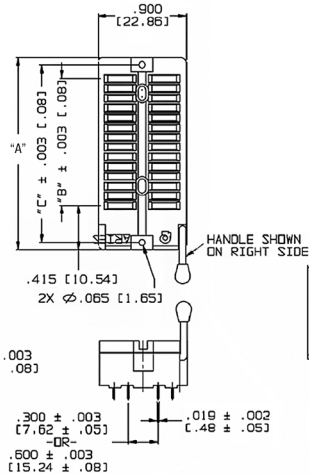
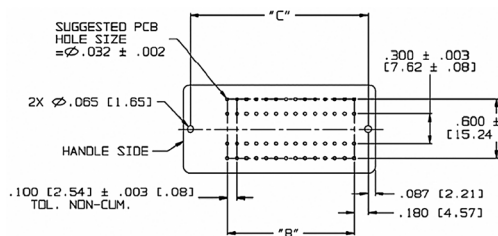
XX-X55X-X X

- Plating**
 - 0 = Sn over Ni
 - OTL = Sn/Pb over Ni
 - 1 = Au over Ni
 - 6 = NiB (Spinodal only)
- Termination**
 - 1 = Solder Pin Tail
- Handle Options**
 - 1 = Left up is closed
 - 2 = Right up is closed
 - 3 = Left down is closed
 - 4 = Right down is closed (std)
- Row-to-Row Spacing (btm)**
 - 3 = 0.300 [7.62]
 - 6 = 0.600 [15.24]
- No. of Pins**
 - 24, 28, 32, 36, 40, 42, 44, 48

MOUNTING CONSIDERATIONS

- See Socket Footprint

"A" = (NO. OF PINS PER ROW x 0.100 [2.54]) + 0.590 [14.99]
 "B" = (NO. OF PINS PER ROW - 1) x 0.100 [2.54]
 "C" = (NO. OF PINS PER ROW x 0.100 [2.54]) + 0.415 [10.54]



ALL DIMENSIONS: INCHES [MILLIMETERS]
 ALL TOLERANCES: ± 0.005 [0.13] UNLESS OTHERWISE SPECIFIED
 FOR TEST SOCKET RECEPTACLES, SEE [DATA SHEET 10003](#)
 DO NOT USE THIS SOCKET IN A BURN-IN OVEN WITH CONTACTS IN OPEN POSITION, AS IT WILL DAMAGE THE SOCKET
 CONSULT FACTORY FOR OTHER SIZES AND CONFIGURATIONS

CUSTOMIZATION: ARIES SPECIALIZES IN CUSTOM DESIGN AND PRODUCTION. SPECIAL MATERIALS, PLATINGS, SIZES, AND CONFIGURATIONS CAN BE FURNISHED, DEPENDING ON QUANTITY.
 ARIES RESERVES THE RIGHT TO CHANGE PRODUCT GENERAL SPECIFICATIONS WITHOUT NOTICE
 PRINTOUTS OF THIS DOCUMENT MAY BE OUT-OF-DATE AND SHOULD BE CONSIDERED UNCONTROLLED